

Electronic Patent Application Fee Transmittal

Application Number:	10797003			
Filing Date:	11-Mar-2004			
Title of Invention:	MOLD DIE FOR A SEMICONDUCTOR DEVICE			
First Named Inventor/Applicant Name:	Akiji Shibata			
Filer:	Alan Edwin Schiavelli/Ricardo Perez			
Attorney Docket Number:	503.43552X00			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	4	3	12
Total in USD (\$)				1752